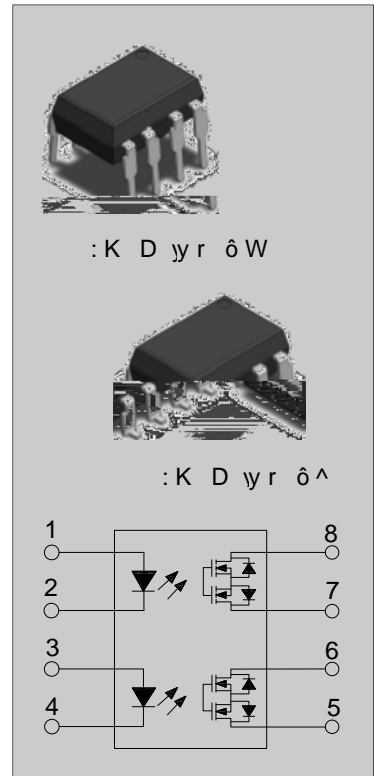




The products are 8-pin optical relays. The device consists of an AlGaAs infrared emitting diode input stage optically coupled to a high-voltage output detector circuit in a plastic DIP8 package with different lead forming options. The detector consists of a high-speed photovoltaic diode array and driver circuitry. The products are widely used in isolation in high-speed inspection machines, telephones equipment and computers.



High isolation 5000 Vrms

Operating temperature range -40°C to 110°C

REACH & RoHS compliance

HBM: H3A; MM: M4; CDM: C3

CQC approved

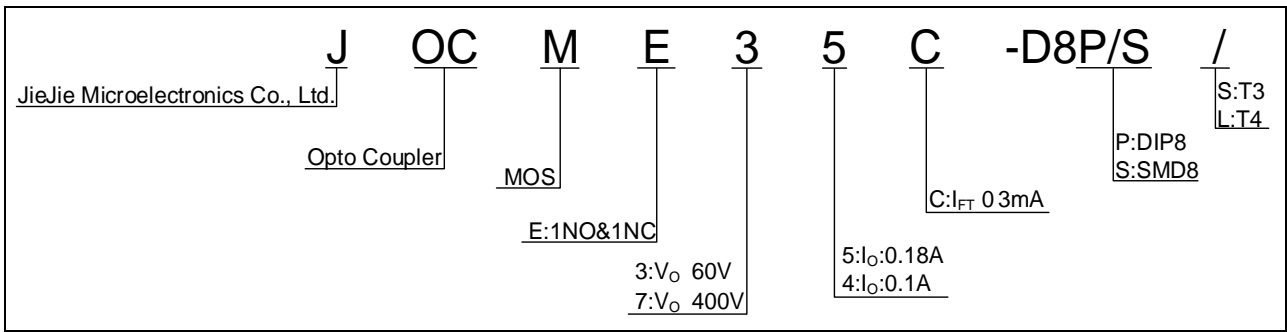
VDE approved

UL approved

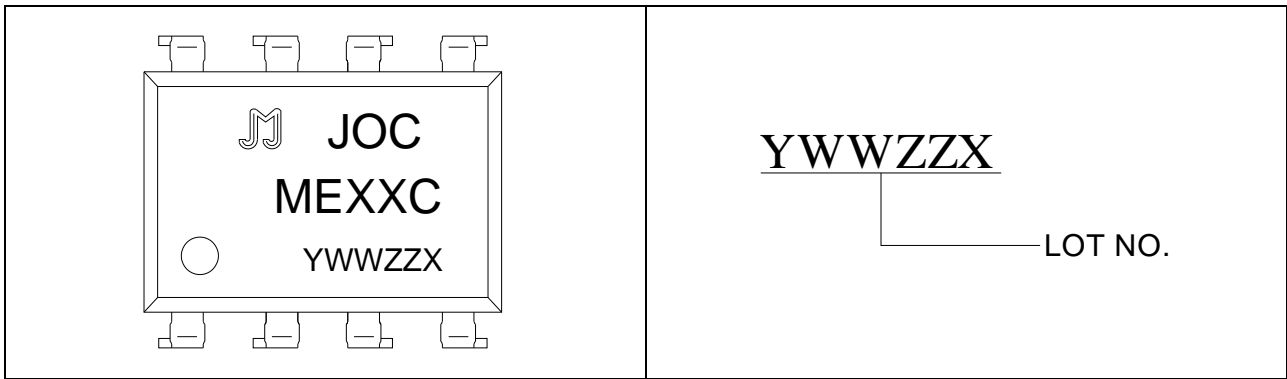
(Temperature=25°C)

Parameter		Symbol	Value	Unit
Input	Forward Current	$I_F$	50	mA
	Peak Forward Current	$I_{FP}$	1 <sup>7</sup>	A
	Reverse Voltage	$V_R$	6	V
	Input Power Dissipation	$P_D$	75	mW
Output	Load Voltage	JOCME35C	60	V
		JOCME74C	400	
	Continuous load current	JOCME35C	0.18	A
		JOCME74C	0.1	
Output Power Dissipation	$P_O$	800	mW	
Total Power Dissipation		$P_{tot}$	875	mW
Isolation Voltage		$V_{iso}$	5000 <sup>8</sup>	Vrms
Operating Temperature		$T_{opr}$	-40~110	
Junction Temperature		$T_j$	125	
Storage Temperature		$T_{stg}$	-40~125	

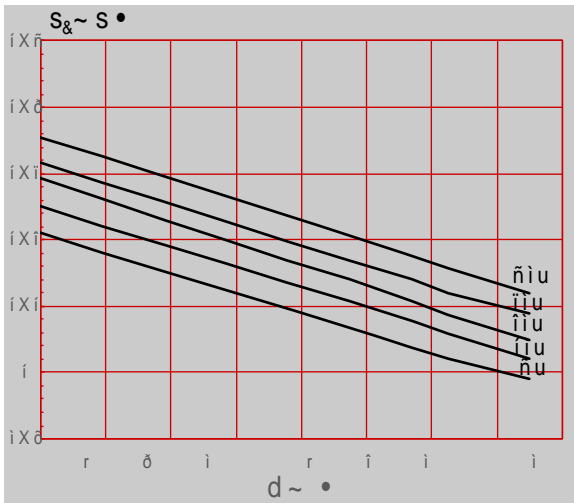




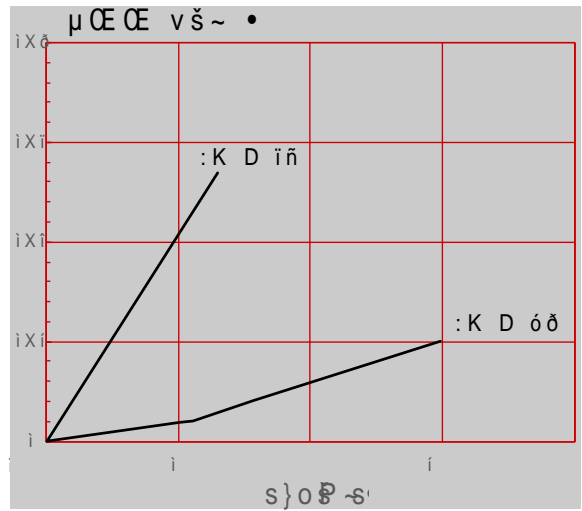
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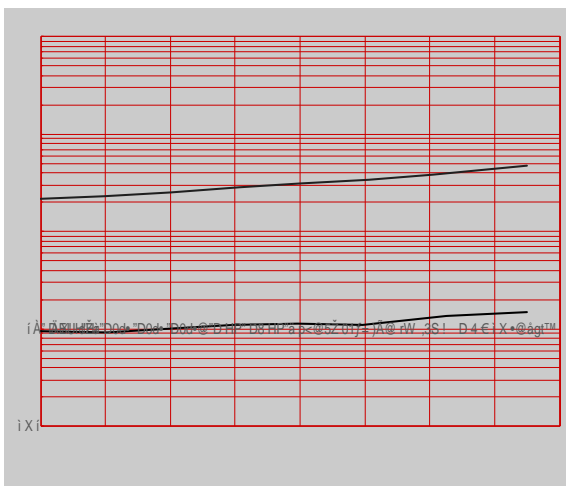
**FIG.1:** LED Dropout Voltage vs. Ambient Temperature



**FIG.2:** Output Current vs. Output Voltage



**FIG.3:** On Resistance vs. Ambient Temperature



**FIG.4:** Load Current vs. Ambient Temperature

FIG.7: Turn On Time vs. Ambient Temperature

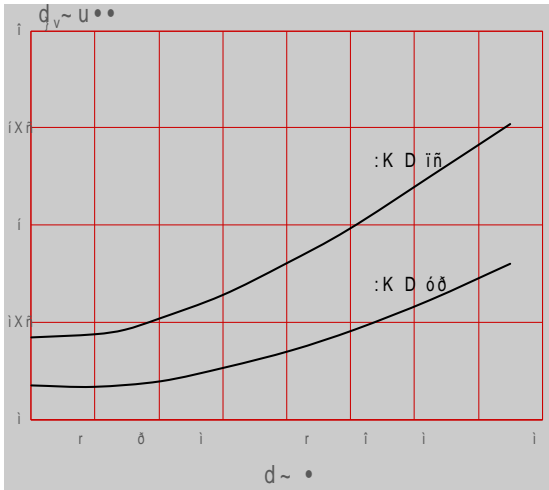


FIG.8: Turn Off Time vs. Ambient Temperature

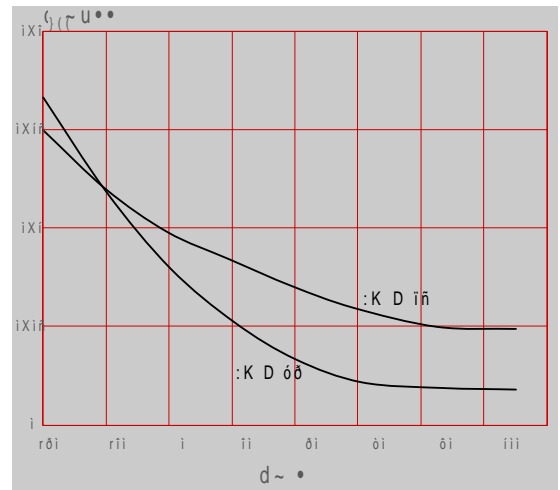


FIG.9: Turn On Time vs. LED Forward Current

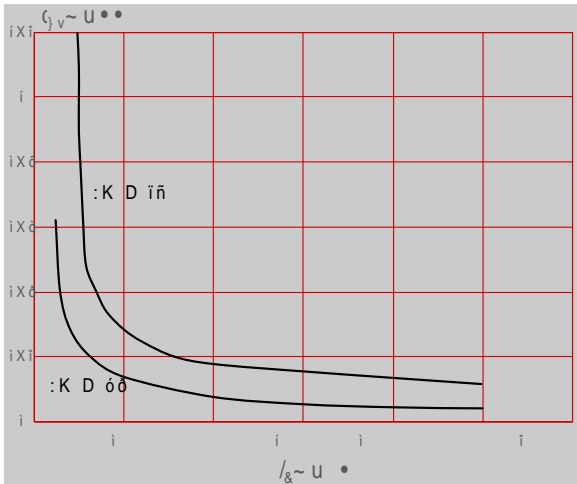


FIG.10: Turn Off Time vs. LED Forward Current

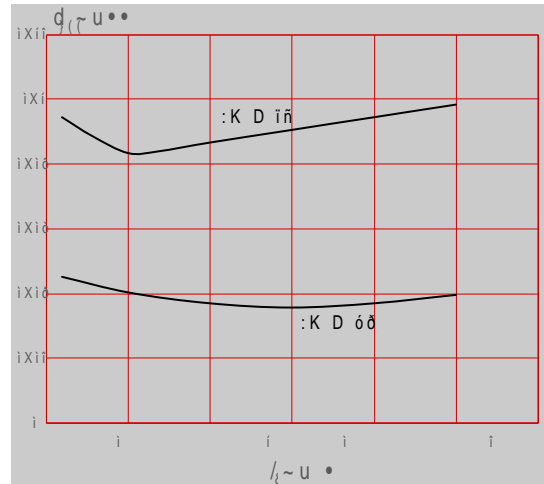


FIG.11: Off State Leakage Current vs. Load Voltage

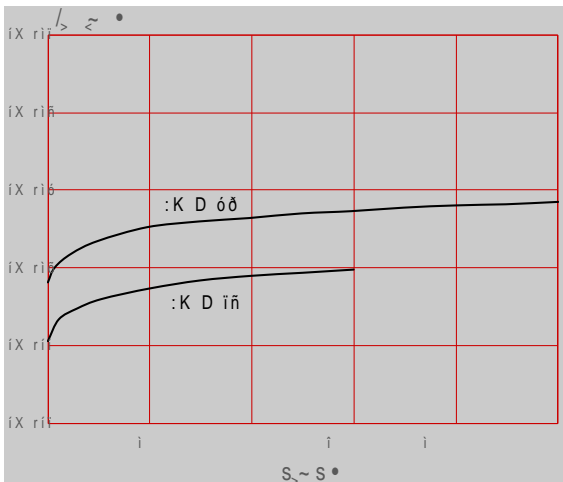
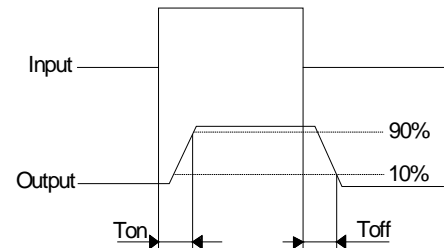
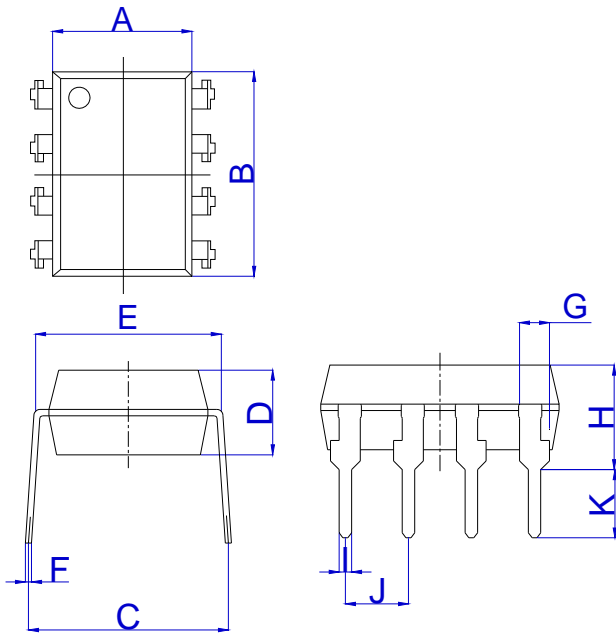


Fig.12: Turn on/Turn off time

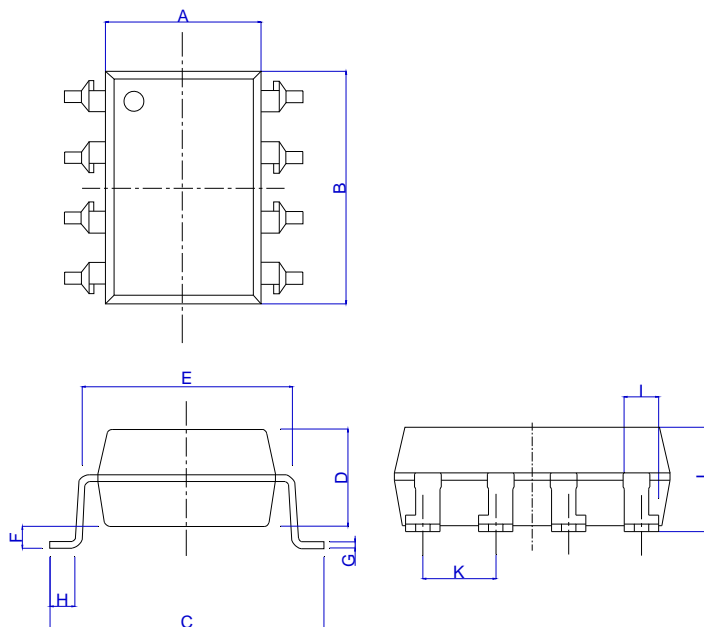


**Standard DIP Type:**



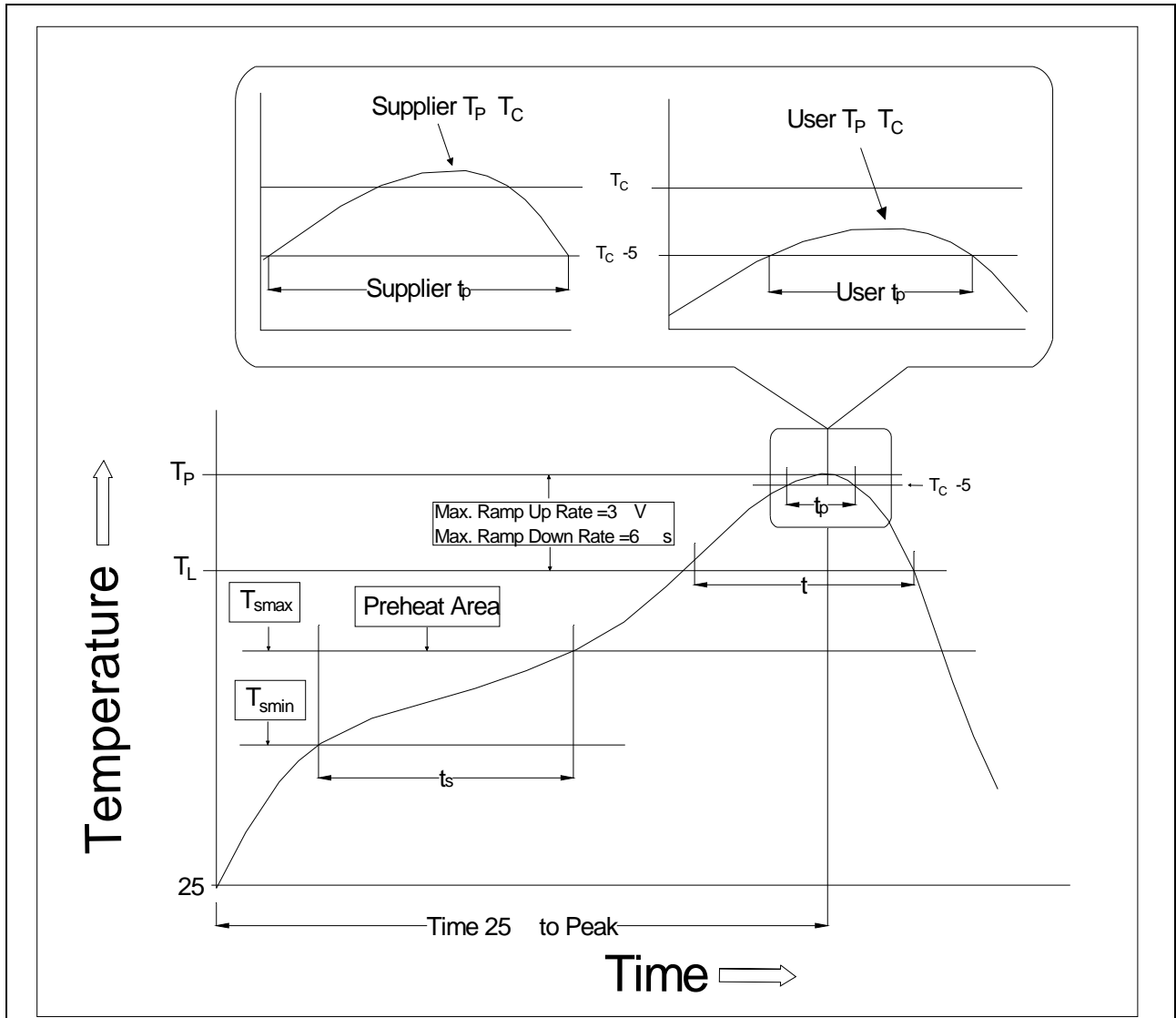
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.60	0.244		0.260
B	9.40		9.80	0.370		0.386
C	7.15		8.95	0.281		0.352
D	3.20		3.60	0.126		0.142
E	7.32		7.92	0.288		0.312
F	0.15		0.35	0.006		0.014
G	0.90		1.50	0.035		0.059
H	3.90		4.50	0.154		0.177
I	0.40		0.60	0.016		0.024
J	2.29		2.79	0.090		0.110
K	2.24		3.24	0.088		0.128

**Option SMD Type:**

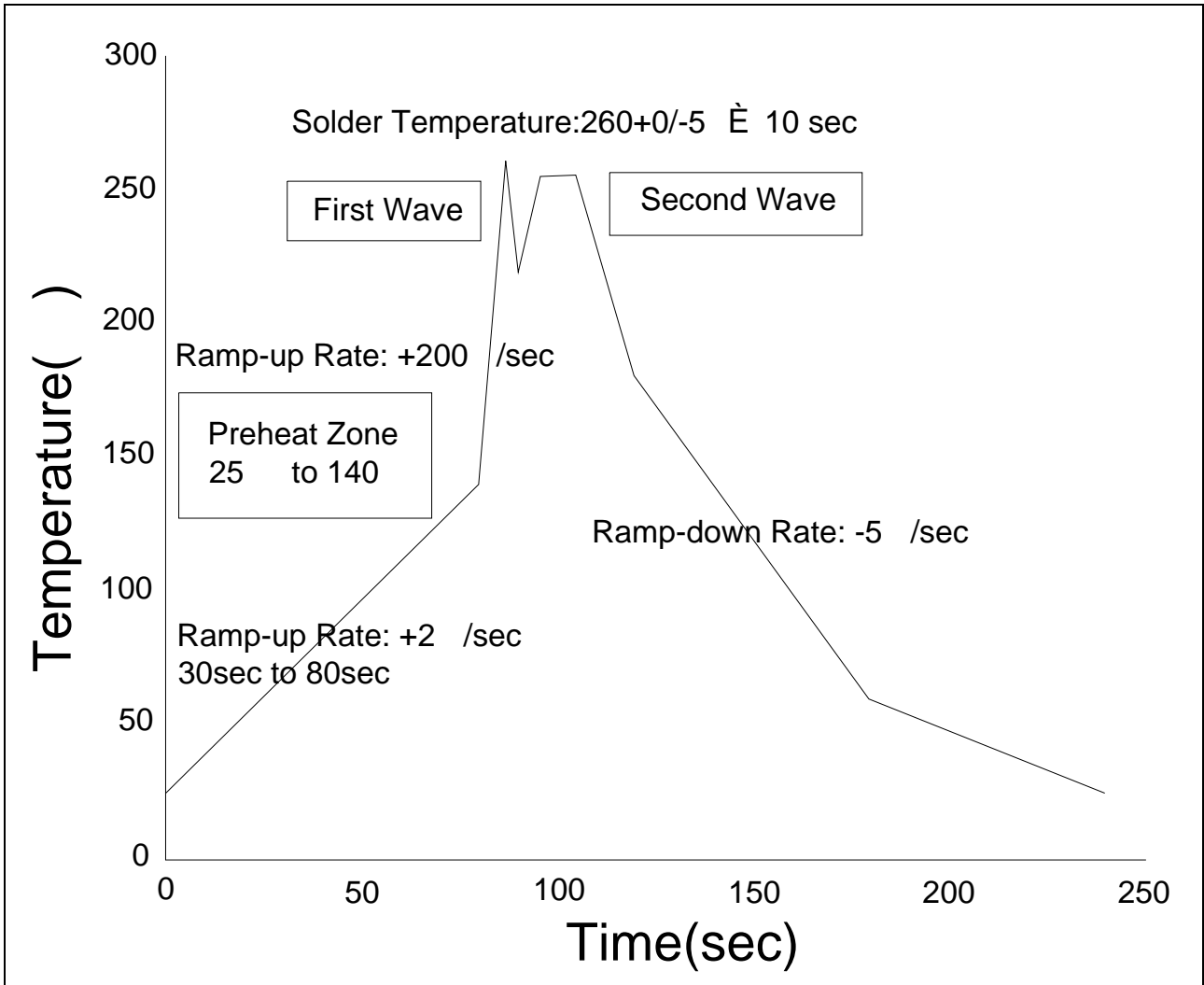


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.60	0.244		0.260
B	9.40		9.80	0.370		0.386
C	9.50		10.50	0.374		0.413
D	3.20		3.60	0.126		0.142
E	7.32		7.92	0.288		0.312
F	0.05		0.35	0.002		0.014
G	0.16		0.36	0.006		0.014
H	0.60		1.40	0.024		0.055
I	0.90		1.50	0.035		0.059
J	3.30		3.90	0.130		0.154
K	2.29		2.79	0.090		0.110





Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. ( $T_{smin}$ )	100	150
Temperature Max. ( $T_{smax}$ )	150	200
Time ( $t_s$ ) from ( $T_{smin}$ to $T_{smax}$ )	60-120 seconds	60-120 seconds
Ramp-up Rate ( $t_L$ to $t_P$ )	3 /second max.	3 /second max.
Liquidus Temperature ( $T_L$ )	183	217
Time ( $t_L$ ) Maintained Above ( $T_L$ )	60-150 seconds	60-150 seconds
Peak Body Package Temperature	235 +0 /-5	260 +0 /-5
Time ( $t_P$ ) within 5 of 260	20 seconds	30 seconds
Ramp-down Rate ( $T_P$ to $T_L$ )	6 /second max.	6 /second max.
Time 25 to Peak Temperature	6 minutes max.	8 minutes max.




Soldering Temperature	360 f5
Soldering Time	3s max.

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.
2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.
3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.
4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.
5. The component has a shelf life of one year when stored under standard conditions.
6. Recommend storage Temp.: 0~40°C;  
Recommend storage humidity: <60%;  
MSL level: MSL 1

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